

TE Internal #: 2294408-1

SFP, SFP+ & zSFP+, Cage Assembly, Data Rate (Max) 32 Gb/s, Internal/External EMI Springs, With Lightpipe, 1 x 8, Dual Round,

Standard, Standard

View on TE.com >



Connectors > Pluggable IO Connectors & Cages > SFP, SFP+ & zSFP+ > zSFP+ Cage Assembly: EMI Springs



Pluggable I/O Product Type: Cage Assembly

Data Rate (Max): 32 Gb/s

EMI Containment Feature Type: Internal/External EMI Springs

Lightpipe Options: With Lightpipe
Port Matrix Configuration: 1 x 8

All zSFP+ Cage Assembly: EMI Springs (25)

Features

Product Type Features

Form Factor	zSFP+
Cage Type	Ganged
Thermal Accessory Type Included	Heat Sink
Pluggable I/O Product Type	Cage Assembly
Lightpipe Options	With Lightpipe
Connector System	Cable-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Lightpipe Configuration Dual Round	
Lightpipe Style Standard	
Lightpipe Profile Standard	
Number of Ports 8	

Electrical Characteristics

Data Rate (Max)	32 Gb/s	



Body Features

Heat Sink Finish	Electroless Nickel
Heat Sink Height Class	Networking Short
Heat Sink Height	9.1 mm[.358 in]
Heat Sink Style	Pin

Termination Features

Termination Post & Tail Length	2.05 mm[.081 in]
Termination Method to Printed Circuit Board	Through Hole - Press-Fit

Mechanical Attachment

Housing Features

Caga Matarial	Nickal Cilvar Allay
Cage Material	Nickel Silver Alloy

Dimensions

Usage Conditions

Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]

Operation/Application

Heat Sink Compatible	Yes
For Use With Pluggable I/O Products	zSFP+ SMT Connector
Circuit Application	Signal

Packaging Features

Packaging Mothod	Tray	
Packaging Method	Tray	

Other

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235)



Candidate List Declared Against: JAN 2023 (233)

Does not contain REACH SVHC

Halogen Content

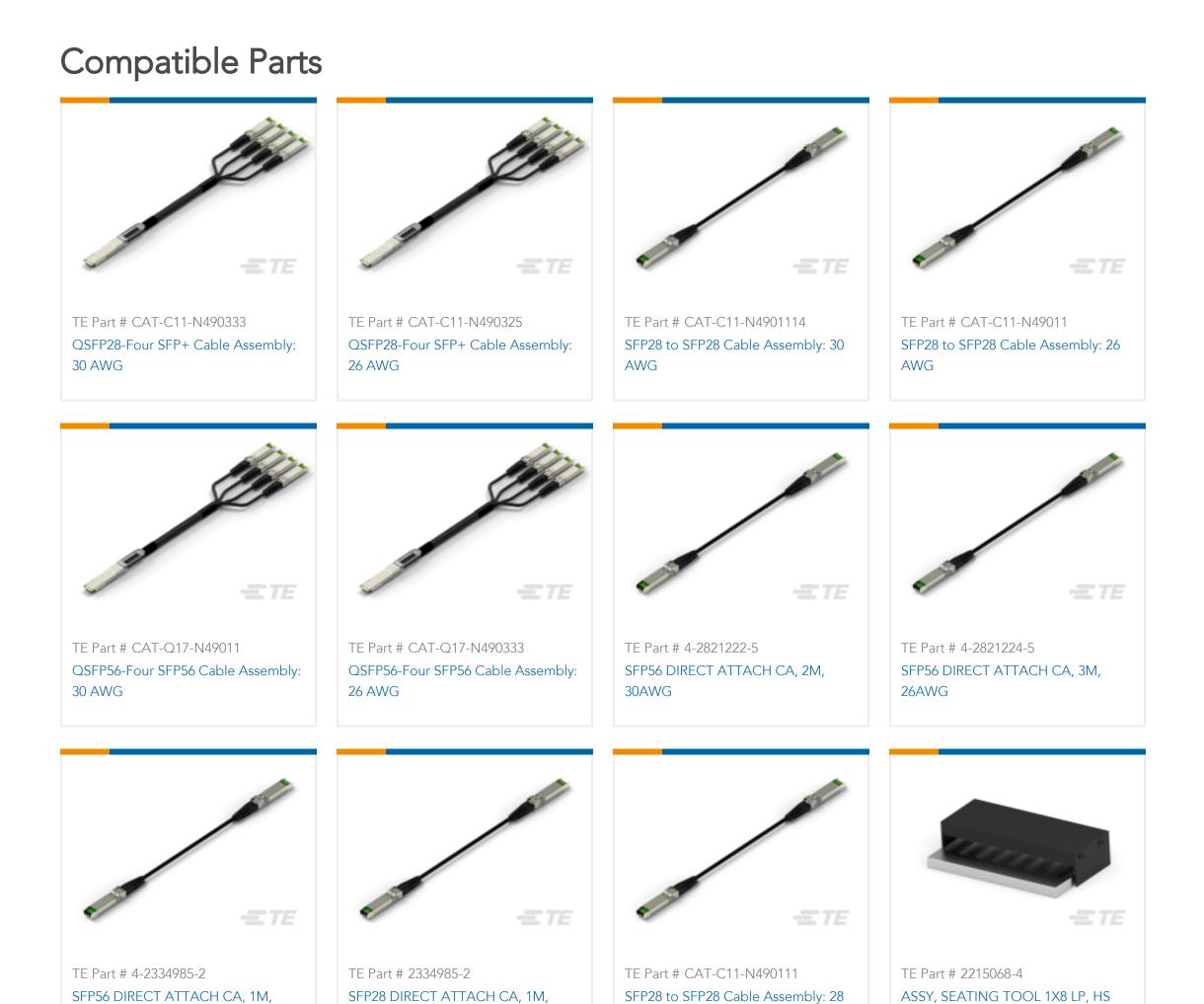
Not Low Halogen - contains Br or Cl > 900 ppm.

Solder Process Capability

Not applicable for solder process capability

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



AWG

32AWG

32AWG



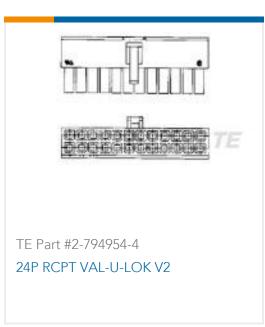
Customers Also Bought













.5FHP08H,440,B,GIG,08/Sn,HT,NSYes







Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2294408-1_B.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_2294408-1_B.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2294408-1_B.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use

Datasheets & Catalog Pages

zSFP+ Interconnect Brochure

English

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Product Environmental Compliance

TE Material Declaration

English